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4/15/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 7293
Morio GAKU et al. : Docket No. 2000-1503A
Serial No. 09/699,419 : Group Art Unit 1765
Filed October 31, 2000 : Examiner Shamim Ahmed

RECEIVED
APR 14 2003
GROUP 1700

COPPER-CLAD BOARD SUITABLE FOR
MAKING HOLE WITH CARBON DIOXIDE
GAS LASER, METHOD OF MAKING HOLE
IN SAID COPPER-CLAD BOARD AND PRINTED
WIRING BOARD COMPRISING SAID COPPER-CLAD
BOARD

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

RESPONSE

Assistant Commissioner for Patents,
Washington, D.C.

Sir:

In response to Official Action dated November 6, 2002, the period for response having been extended for two (2) months by the attached petition, please amend the present application as follows:

IN THE CLAIMS:

Kindly amend claim 15 as follows:

B' 15. (Amended) A method of making a hole in a copper-clad board, in which a surface of the metallic-treatment layer of the copper-clad board recited in claim 1, which layer contains nickel as an essential element, is directly irradiated with a carbon dioxide gas laser having an energy sufficient for processing a copper foil by means of the pulse oscillation of the carbon